

Adhesive bonding can replace soldering in power modules



Adhesive bonding of power modules can often be an alternative to usual joining

techniques. [Epoxy-based adhesives](#) can generally produce high-strength and stable connections. Whether this also applies to the high requirements in power circuits was the subject of a research project recently performed by the IMTEK Department of Microsystems Engineering and the IESY Institute of Electric Power Systems at the University Freiburg and Magdeburg respectively. Some of the project output has been published in an [article in Volume 14, Issue 2, June 2017 edition of *Adhesion* magazine](#), authored by our friend Dr. Arno Maurer of [Polytec PT](#).

The conclusion? “Overall, the project shows a significant advance in the development of adhesives for power electronics in comparison to the state of the art a few years ago.”

Adhesive bonding can replace soldering in power modules

Supplied by:

intertronics

INTERTRONICS

12a Station Field Industrial Estate, Banbury Road, Kidlington

Oxfordshire England OX5 1JD

t 01865 842842 e info@intertronics.co.uk

Last updated: August 2017

Statements, technical information and recommendations contained herein are based on tests we believe to be reliable but they are not to be construed in any manner as warranties expressed or implied. The user shall determine the suitability of the product for his intended use and the user assumes all risk and liability whatsoever in connection therewith.